30-P212PMA100M7-L880A79Y

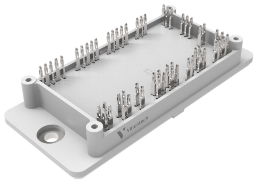
datasheet

***flow*PIM 2** **1200 V / 100 A**

Features

- IGBT M7 with low VCEsat and improved EMC behavior
- Open emitter configuration
- Compact and low inductive design
- Built-in NTC

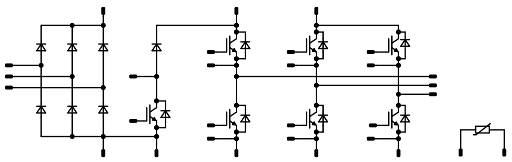
flow 2 17 mm housing



Target applications

- Industrial Drives

Schematic



Types

- 30-P212PMA100M7-L880A79Y

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Inverter Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s = 80 °C	116	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	222	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 800 V	T_j = 150 °C	9,5	µs
Maximum junction temperature	T_{jmax}			175	°C
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	87	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	165	W
Maximum junction temperature	T_{jmax}			175	°C
Brake Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$	T_s = 80 °C	94	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		150	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	190	W
Gate-emitter voltage	V_{GES}			±20	V
Maximum junction temperature	T_{jmax}			175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Brake Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	41	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		70	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	80	W
Maximum junction temperature	T_{jmax}			175	°C
Brake Sw. Protection Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	13	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}		10	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	34	W
Maximum junction temperature	T_{jmax}			175	°C
Rectifier Diode					
Peak repetitive reverse voltage	V_{RRM}			1600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$	T_s = 80 °C	126	A
Surge (non-repetitive) forward current	I_{FSM}	Single Half Sine Wave, t_p = 10 ms	T_j = 150 °C	890	A
Surge current capability	I^2t			3960	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	156	W
Maximum junction temperature	T_{jmax}			150	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Module Properties					
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…+(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
Isolation voltage	V_{isol}	AC Voltage	t_p = 1 min	2500	V
Creepage distance				>12,7	mm
Clearance				11,72	mm
Comparative Tracking Index	CTI			≥ 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,01	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		100	25 125 150		1,53 1,71 1,75	1,85(1)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			100	µA
Gate-emitter leakage current	I_{GES}		20	0		25			0,5	µA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}		0	10		25		21000		pF
Output capacitance	C_{oes}							700		pF
Reverse transfer capacitance	C_{res}							280		pF
Gate charge	Q_g	V_{CC} = 600 V	15		100	25		700		nC
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,43		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 2 Ω R_{goff} = 2 Ω	±15	600	100	25 125 150		118,2 118,2 117,6		ns
Rise time	t_r					25 125 150		10,2 12,4 13,4		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		173,6 200,4 205,6		ns
Fall time	t_f					25 125 150		82,85 96,38 106,77		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=11,6 µC Q_{rFWD}=17,27 µC Q_{rFWD}=19,18 µC				25 125 150		3,26 4,87 5,37		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		6,6 8,77 9,49		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				100	25 125 150		1,82 1,96 1,97	2,1[1]	V
Reverse leakage current	I_R	V_r = 1200 V				25			40	µA
Thermal										
Thermal resistance junction to sink [2]	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,58		K/W
Dynamic										
Peak recovery current	I_{RRM}	d*i*/d*t*=9387 A/µs d*i*/d*t*=7872 A/µs d*i*/d*t*=8350 A/µs	±15	600	100	25 125 150		178,25 165,9 164,61		A
Reverse recovery time	t_{rr}					25 125 150		149,24 311,54 339,17		ns
Recovered charge	Q_r					25 125 150		11,6 17,27 19,18		µC
Reverse recovered energy	E_{rec}					25 125 150		5,14 7,75 8,59		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		4044 2649 2147		A/µs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Values Min	Values Typ	Values Max	Unit
Brake Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,0075	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		75	25 125 150		1,55 1,7 1,75	1,9(1)	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			100	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							4		Ω
Input capacitance	C_{ies}		0	10		25		16000		pF
Output capacitance	C_{oes}		0	10		25		480		pF
Reverse transfer capacitance	C_{res}		0	10		25		190		pF
Gate charge	Q_g	V_{CC} = 600 V	15		75	25		570		nC
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,5		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 4 Ω R_{goff} = 4 Ω	0/15	700	75	25 125 150		104,8 105,4 104		ns
Rise time	t_r	R_{gon} = 4 Ω R_{goff} = 4 Ω	0/15	700	75	25 125 150		38,4 44,8 49		ns
Turn-off delay time	$t_{d(off)}$	R_{gon} = 4 Ω R_{goff} = 4 Ω	0/15	700	75	25 125 150		410 464 481		ns
Fall time	t_f	R_{gon} = 4 Ω R_{goff} = 4 Ω	0/15	700	75	25 125 150		68,13 84,88 91,43		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=6,23 µC Q_{rFWD}=8,84 µC Q_{rFWD}=10,01 µC	0/15	700	75	25 125 150		6,77 8,44 8,91		mWs
Turn-off energy (per pulse)	E_{off}		0/15	700	75	25 125 150		5,6 7,79 8,33		mWs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Brake Diode										
Static										
Forward voltage	V_F				35	25 125 150		1,67 1,78 1,78	2,1(1)	V
Reverse leakage current	I_R	V_r = 1200 V				25			40	µA
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,18		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt=1820 A/µs di/dt=1430 A/µs di/dt=1500 A/µs	0/15	700	75	25 125 150		45,4 46,24 46,77		A
Reverse recovery time	t_{rr}					25 125 150		319,01 462,28 500,81		ns
Recovered charge	Q_r					25 125 150		6,23 8,84 10,01		µC
Reverse recovered energy	E_{rec}					25 125 150		2,68 4,03 4,66		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		261,19 258,83 229,88		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Brake Sw. Protection Diode										
Static										
Forward voltage	V_F				5	25 125 150		1,57 1,66 1,65	2,1(1)	V
Reverse leakage current	I_R	V_r = 1200 V				25			20	µA
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						2,76		K/W
Rectifier Diode										
Static										
Forward voltage	V_F				45	25 125 150		1,01 0,929 0,92	1,21(1) 1,1(1)	V
Reverse leakage current	I_R	V_r = 1600 V				25			50	µA
Thermal										
Thermal resistance junction to sink (2)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,45		K/W

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_{F} [V]	I_{C} [A] I_{D} [A] I_{F} [A]	T_{j} [°C]	Min	Typ	Max	
Thermistor										
Static										
Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1484 Ω				100	-5		5	%
Power dissipation	P							5		mW
Power dissipation constant	d					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %						3962		K
B-value	$B_{(25/100)}$	Tol. ±1 %						4000		K
Vincotech Thermistor Reference									I	

(1) Value at chip level

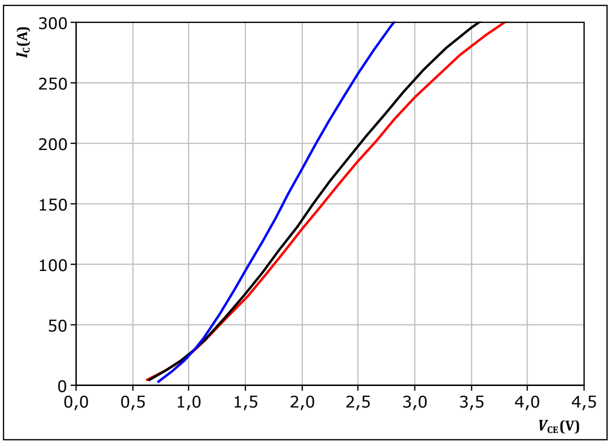
(2) Only valid with pre-applied Vincotech thermal interface material.

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

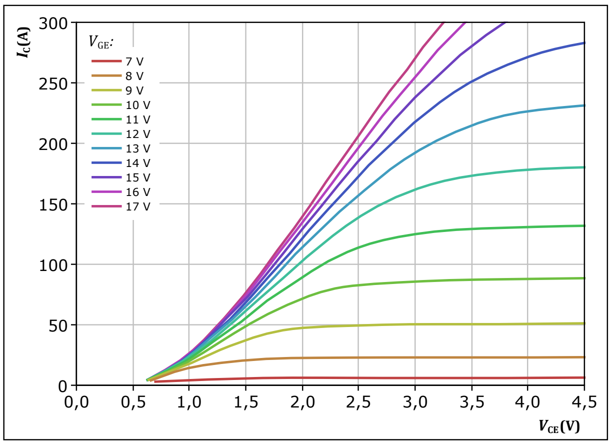


t_p = 250 µs
V_{GE} = 15 V
T_j: 25 °C, 125 °C, 150 °C

figure 2. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

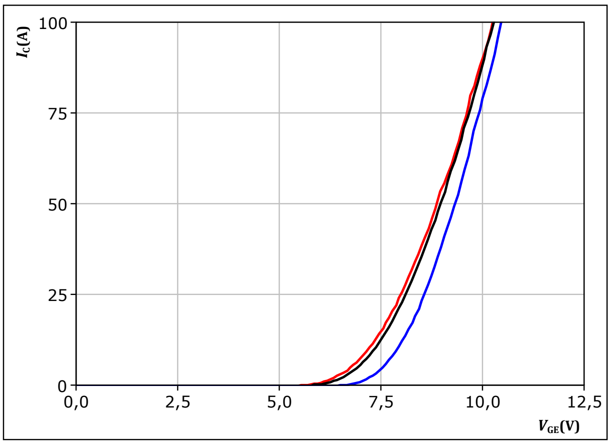


t_p = 250 µs
T_j = 150 °C
V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

I_C = f(V_{GE})

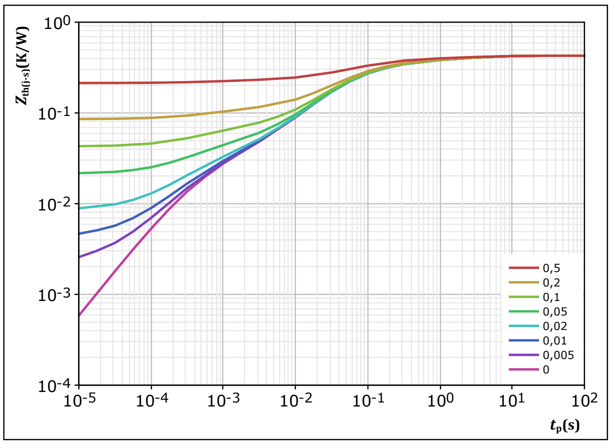


t_p = 250 µs
V_{CE} = 10 V
T_j: 25 °C, 125 °C, 150 °C

figure 4. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T
$R_{th(j-s)}$ = 0,427 K/W

IGBT thermal model values

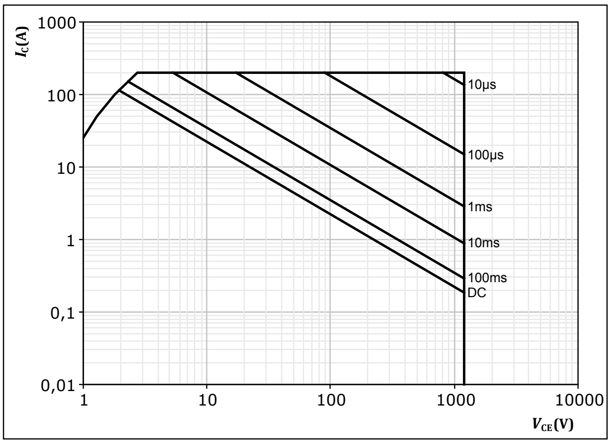
R (K/W)	τ (s)
3,38E-02	4,81E+00
4,26E-02	1,02E+00
7,30E-02	2,26E-01
1,67E-01	6,44E-02
8,34E-02	1,89E-02
1,52E-02	1,20E-03
1,24E-02	3,17E-04

Inverter Switch Characteristics

figure 5.	IGBT

Safe operating area

I_C = f(V_{CE})

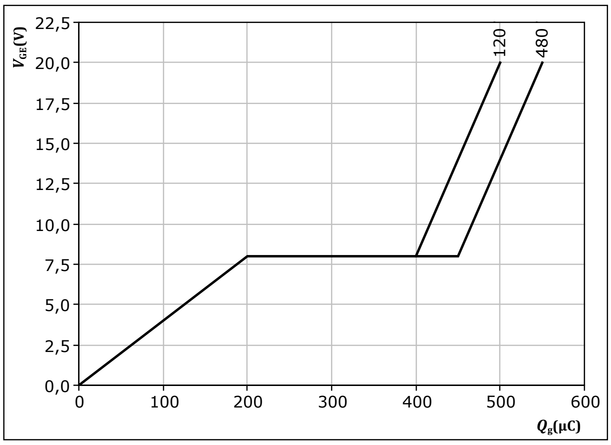


D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

figure 6.	IGBT

Gate voltage vs gate charge

V_{GE} = f(Q_g)



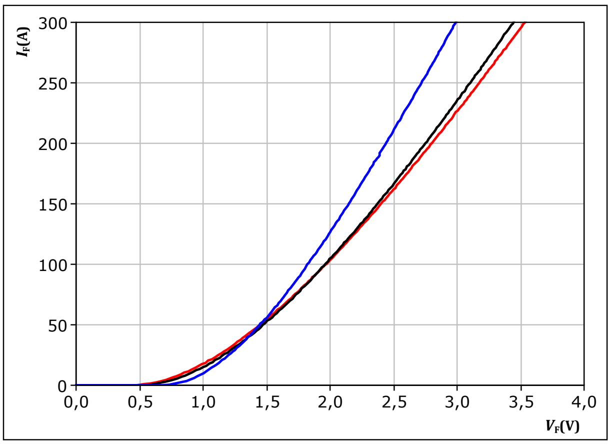
I_C =		A
T_j =	25	°C

Inverter Diode Characteristics

figure 7. **FWD**

Typical forward characteristics

I_F = f(V_F)



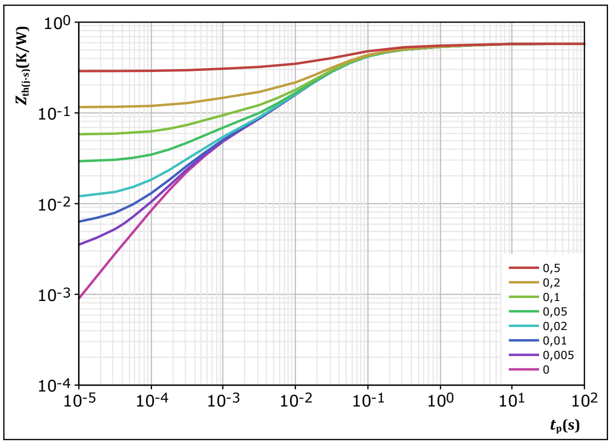
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 8. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 0,578 K/W

FWD thermal model values

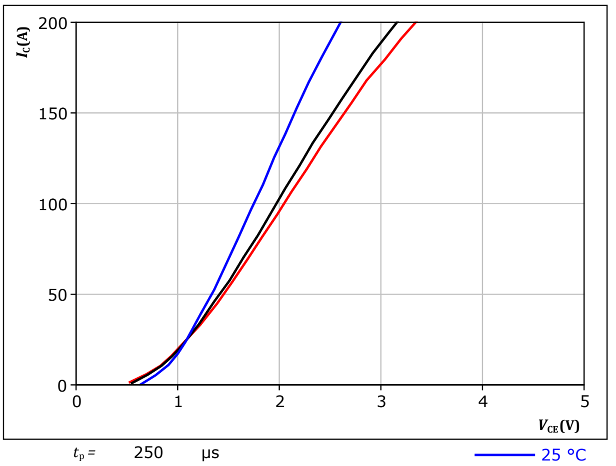
R (K/W)	τ (s)
4,89E-02	3,41E+00
7,07E-02	4,06E-01
2,02E-01	7,46E-02
1,90E-01	2,27E-02
3,24E-02	3,47E-03
3,35E-02	4,78E-04

Brake Switch Characteristics

figure 9. **IGBT**

Typical output characteristics

I_C = f(V_{CE})



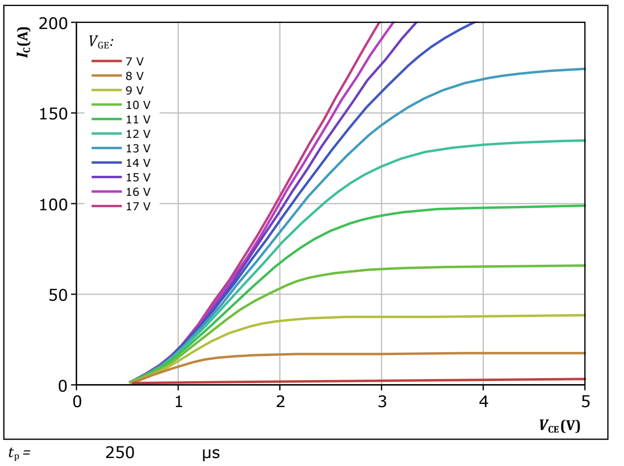
t_p =	250	µs
V_{GE} =	15	V

T_j: 25 °C, 125 °C, 150 °C

figure 10. **IGBT**

Typical output characteristics

I_C = f(V_{CE})



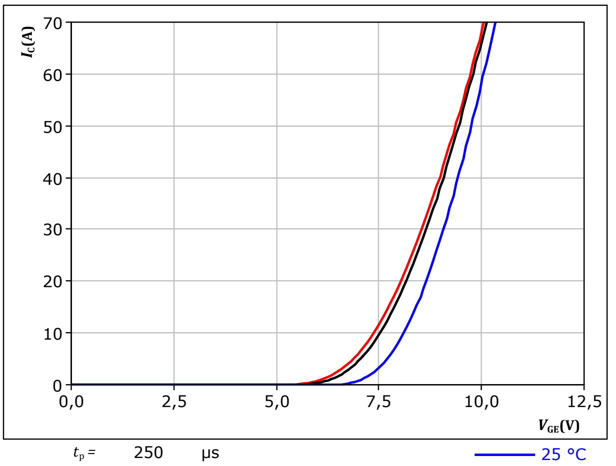
t_p =	250	µs
T_j =	150	°C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 11. **IGBT**

Typical transfer characteristics

I_C = f(V_{GE})



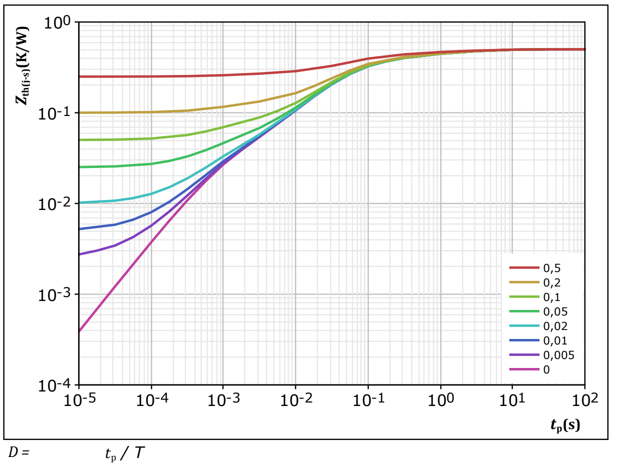
t_p =	250	µs
V_{CE} =	10	V

T_j: 25 °C, 125 °C, 150 °C

figure 12. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D =	t_p / T	
$R_{th(j-s)}$ =	0,5	K/W

IGBT thermal model values

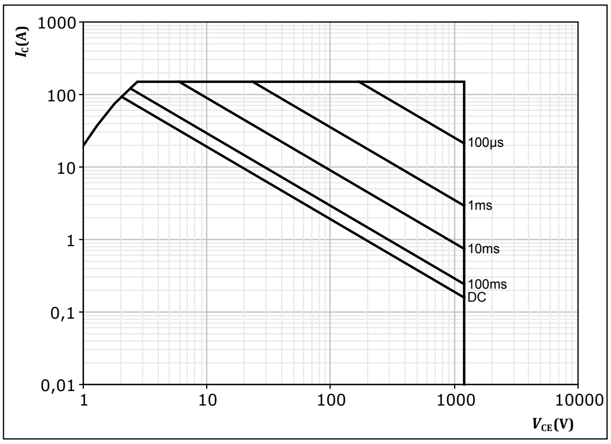
R (K/W)	τ (s)
3,92E-02	4,73E+00
6,01E-02	9,48E-01
1,18E-01	1,70E-01
2,25E-01	3,80E-02
3,32E-02	9,18E-03
2,48E-02	8,63E-04

Brake Switch Characteristics

figure 13.	IGBT

Safe operating area

$I_C = f(V_{CE})$



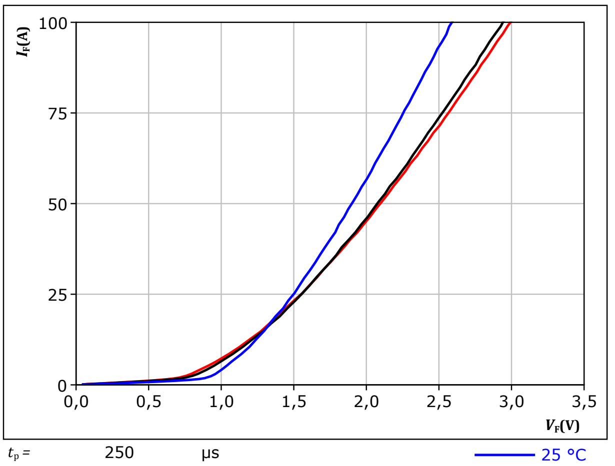
D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Brake Diode Characteristics

figure 14. **FWD**

Typical forward characteristics

I_F = f(V_F)



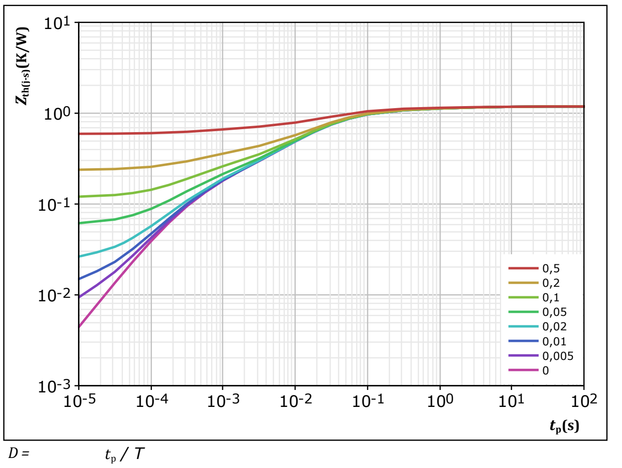
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 15. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 1,185 K/W

FWD thermal model values

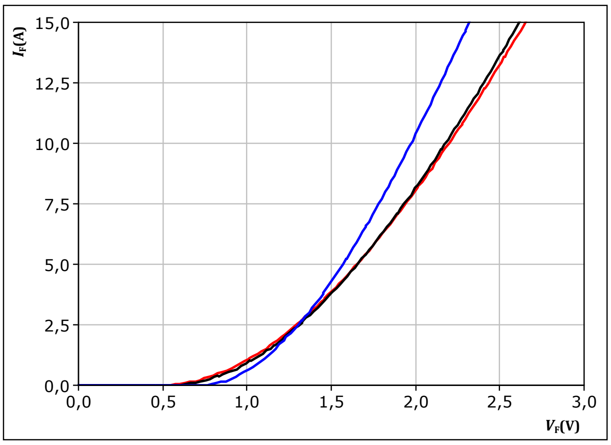
R (K/W)	τ (s)
4,51E-02	5,63E+00
8,94E-02	6,99E-01
2,50E-01	9,25E-02
4,74E-01	2,37E-02
1,69E-01	5,51E-03
1,06E-01	7,12E-04
5,12E-02	2,07E-04

Brake Sw. Protection Diode Characteristics

figure 16. **FWD**

Typical forward characteristics

I_F = f(V_F)



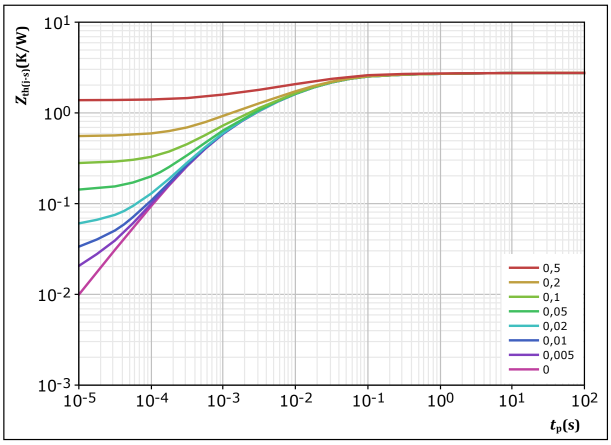
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 17. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T

$R_{th(j-s)}$ = 2,759 K/W

FWD thermal model values

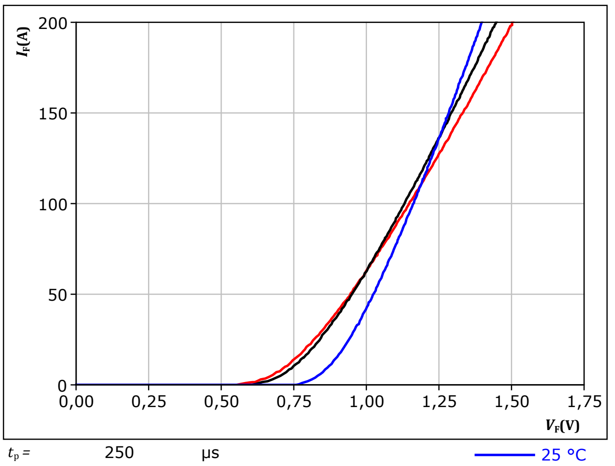
R (K/W)	τ (s)
6,58E-02	4,81E+00
1,43E-01	3,47E-01
6,08E-01	4,61E-02
8,65E-01	1,40E-02
7,08E-01	2,91E-03
3,69E-01	5,42E-04

Rectifier Diode Characteristics

figure 18. **Rectifier**

Typical forward characteristics

$I_F = f(V_F)$



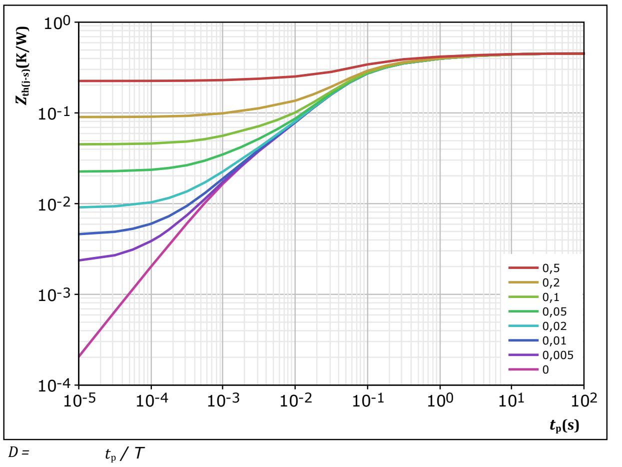
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 19. **Rectifier**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 0,45 K/W

Rectifier thermal model values

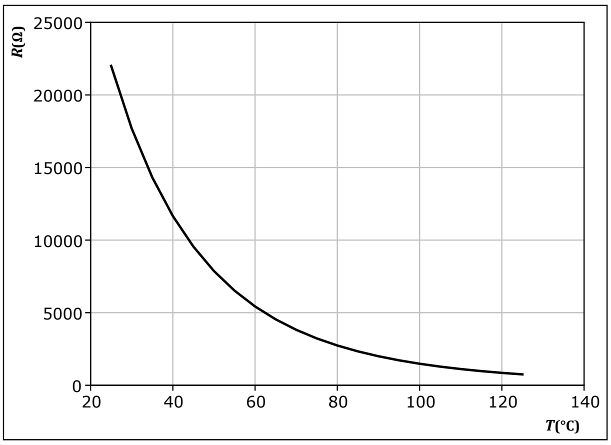
R (K/W)	τ (s)
3,06E-02	7,38E+00
5,87E-02	1,30E+00
1,21E-01	1,90E-01
2,00E-01	4,49E-02
2,12E-02	9,83E-03
1,85E-02	1,38E-03

Thermistor Characteristics

figure 20.	Thermistor

Typical NTC characteristic as function of temperature

R_T = f(T)

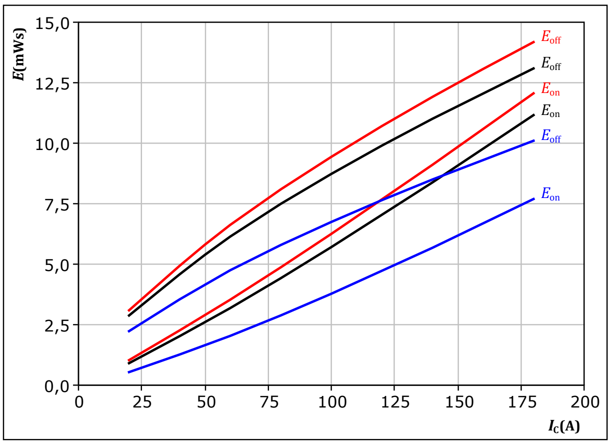


Inverter Switching Characteristics

figure 21. **IGBT**

Typical switching energy losses as a function of collector current

E = f(I_C)



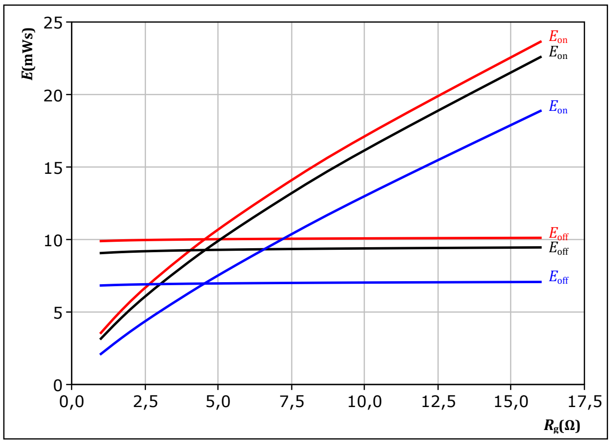
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C (blue)
V_{GE} =	±15	V		125 °C (black)
R_{gon} =	2	Ω		150 °C (red)
R_{goff} =	2	Ω		

figure 22. **IGBT**

Typical switching energy losses as a function of gate resistor

E = f(R_g)



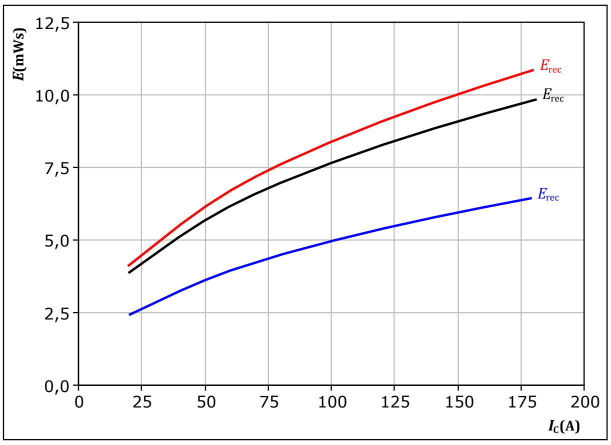
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C (blue)
V_{GE} =	±15	V		125 °C (black)
I_C =	100	A		150 °C (red)

figure 23. **FWD**

Typical reverse recovered energy loss as a function of collector current

E_{rec} = f(I_C)



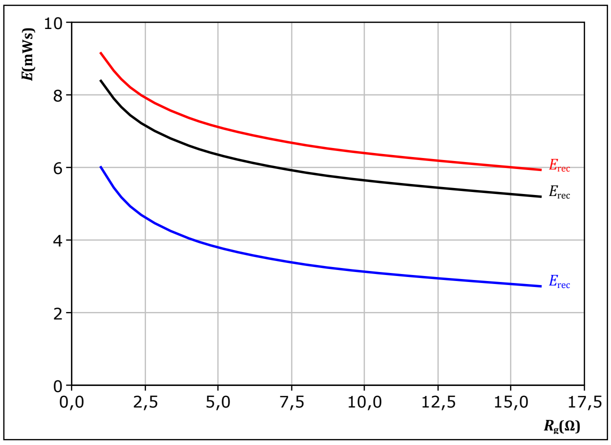
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C (blue)
V_{GE} =	±15	V		125 °C (black)
R_{gon} =	2	Ω		150 °C (red)

figure 24. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

E_{rec} = f(R_g)



With an inductive load at

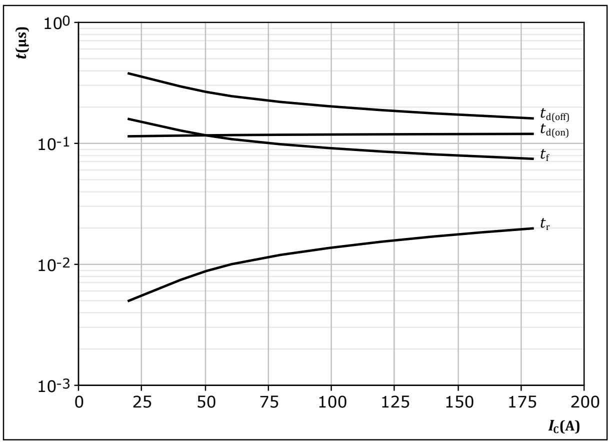
V_{CE} =	600	V	T_j:	25 °C (blue)
V_{GE} =	±15	V		125 °C (black)
I_C =	100	A		150 °C (red)

Inverter Switching Characteristics

figure 25. **IGBT**

Typical switching times as a function of collector current

t = f(I_C)



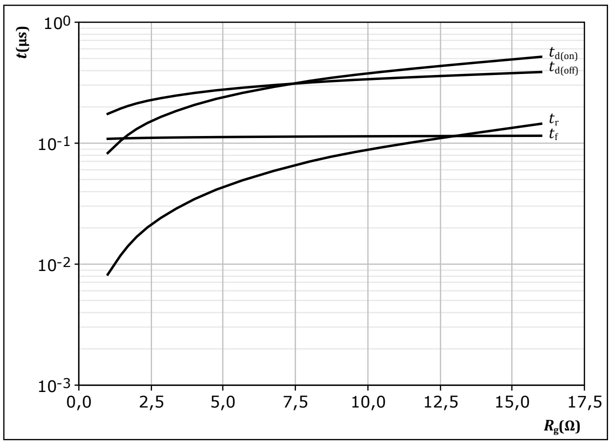
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	2	Ω
R_{goff} =	2	Ω

figure 26. **IGBT**

Typical switching times as a function of gate resistor

t = f(R_g)



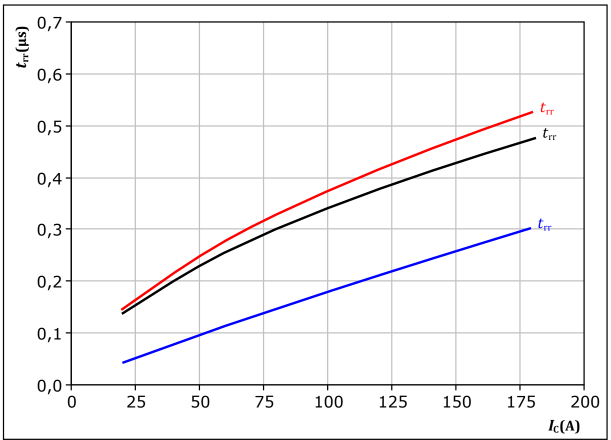
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	100	A

figure 27. **FWD**

Typical reverse recovery time as a function of collector current

t_{rr} = f(I_C)



With an inductive load at

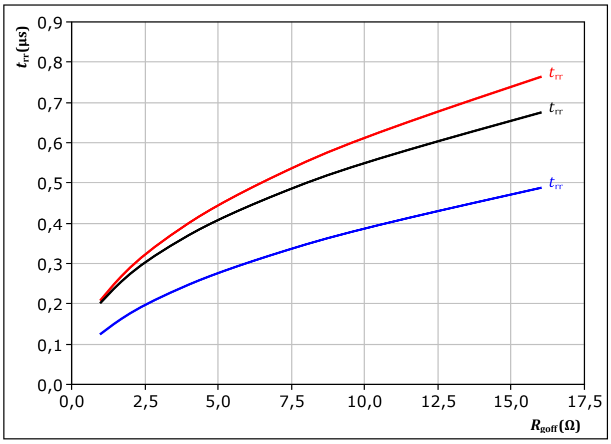
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	2	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 28. **FWD**

Typical reverse recovery time as a function of IGBT turn off gate resistor

t_{rr} = f(R_{goff})



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	100	A

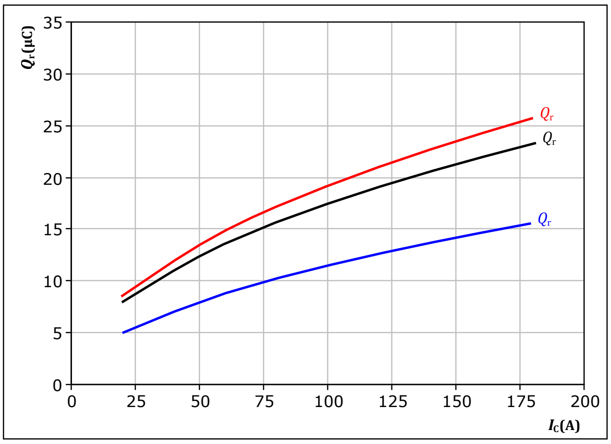
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 29. **FWD**

Typical recovered charge as a function of collector current

Q_r = f(I_C)



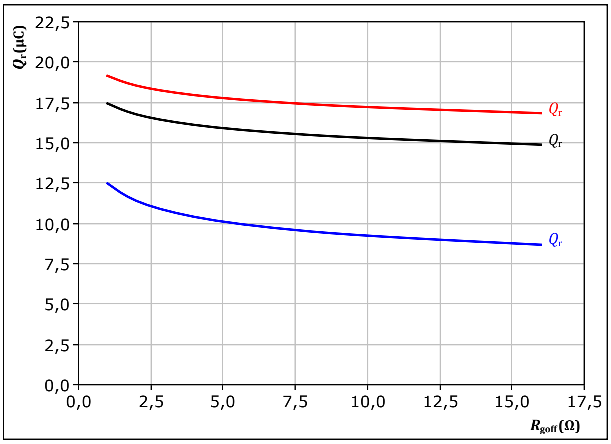
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	2	Ω		150 °C

figure 30. **FWD**

Typical recovered charge as a function of turn off gate resistor

Q_r = f(R_{goff})



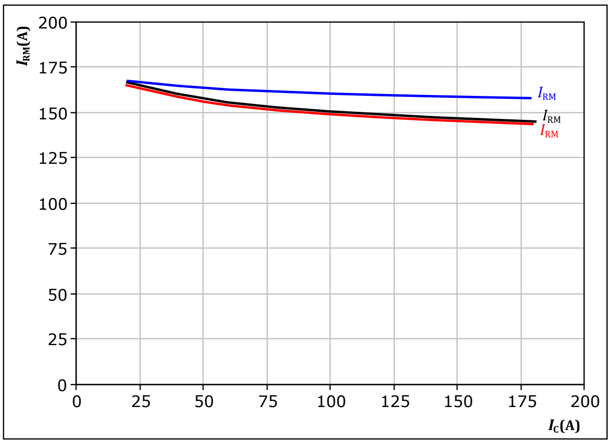
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

figure 31. **FWD**

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



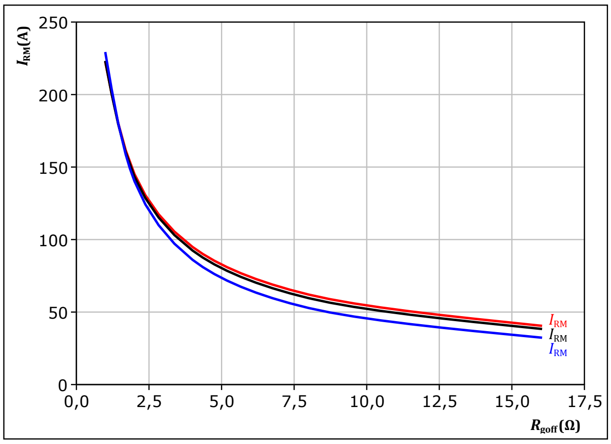
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	2	Ω		150 °C

figure 32. **FWD**

Typical peak reverse recovery current as a function of turn off gate resistor

I_{RM} = f(R_{goff})



With an inductive load at

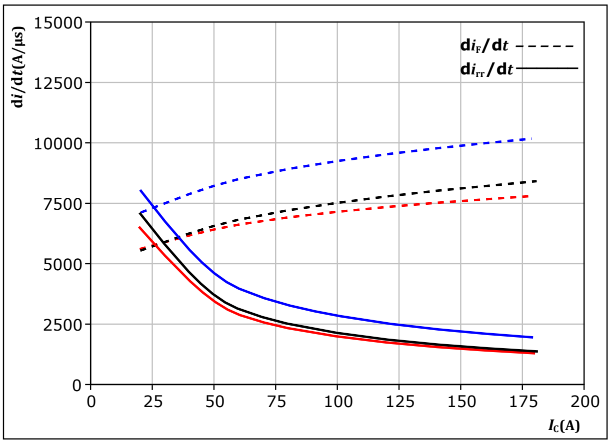
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

Inverter Switching Characteristics

figure 33. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



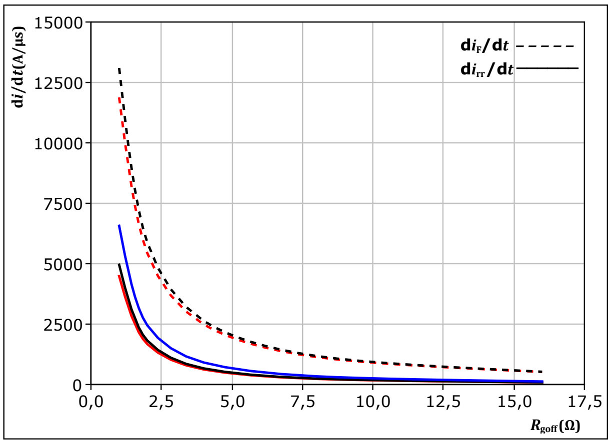
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	2	Ω		150 °C

figure 34. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn off gate resistor

di_F/dt, di_{rr}/dt = f(R_{goff})



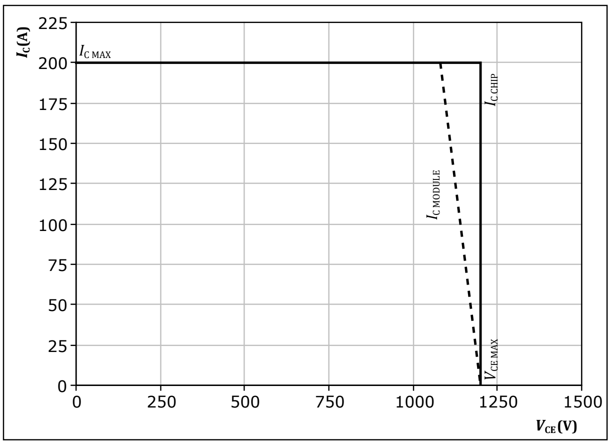
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

figure 35. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



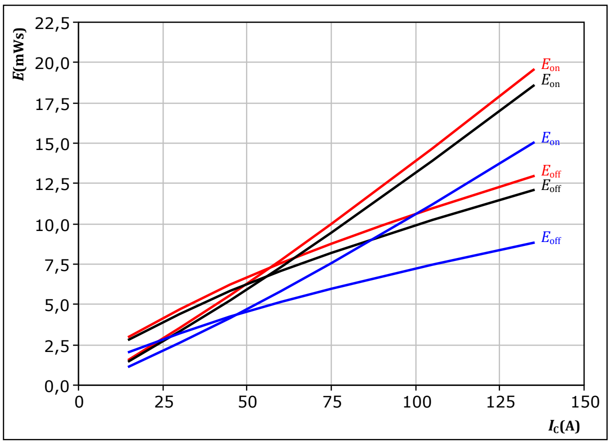
At	T_j =	150	°C
	R_{gon} =	2	Ω
	R_{goff} =	2	Ω

Brake Switching Characteristics

figure 36. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



With an inductive load at

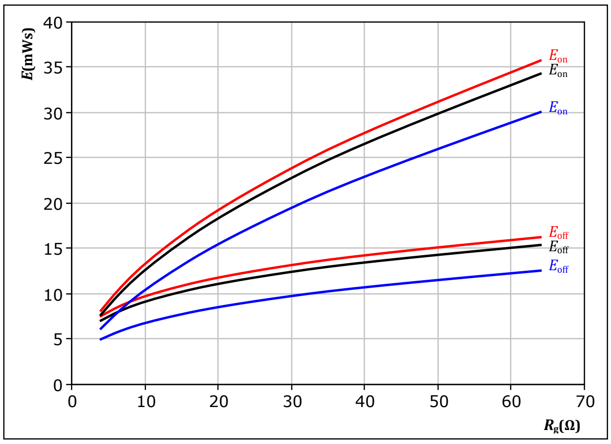
V_{CE} =	700	V
V_{GE} =	0/15	V
R_{gon} =	4	Ω
R_{goff} =	4	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 37. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



With an inductive load at

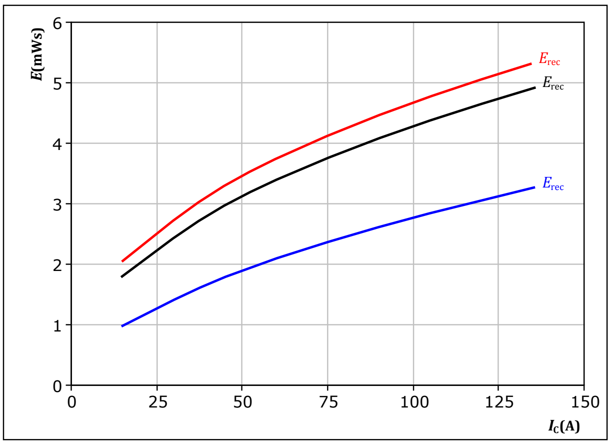
V_{CE} =	700	V
V_{GE} =	0/15	V
I_C =	75	A

T_j: 25 °C, 125 °C, 150 °C

figure 38. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



With an inductive load at

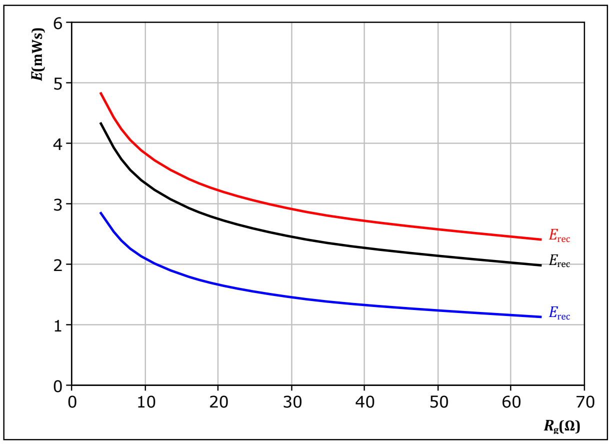
V_{CE} =	700	V
V_{GE} =	0/15	V
R_{gon} =	4	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 39. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

V_{CE} =	700	V
V_{GE} =	0/15	V
I_C =	75	A

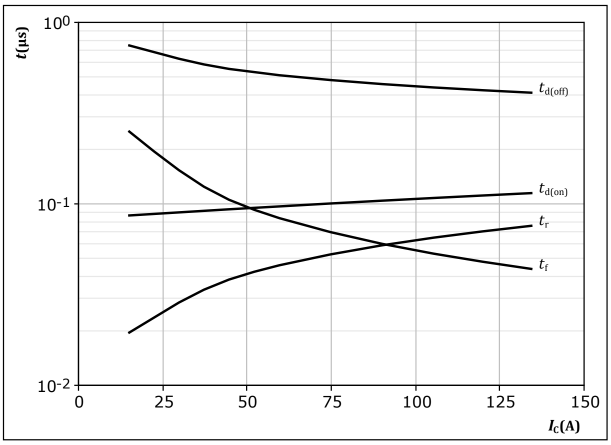
T_j: 25 °C, 125 °C, 150 °C

Brake Switching Characteristics

figure 40. **IGBT**

Typical switching times as a function of collector current

t = f(I_C)



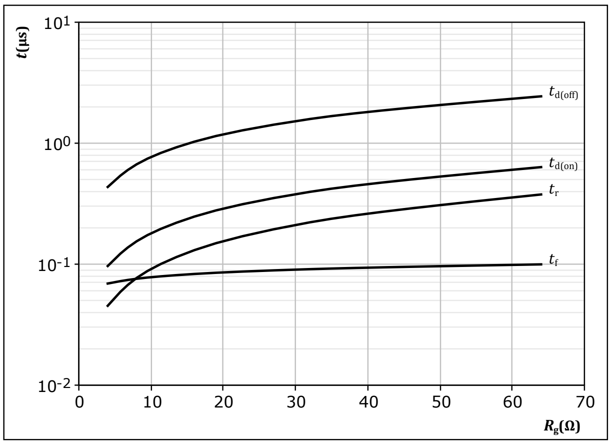
With an inductive load at

T_j =	150	°C
V_{CE} =	700	V
V_{GE} =	0/15	V
R_{gon} =	4	Ω
R_{goff} =	4	Ω

figure 41. **IGBT**

Typical switching times as a function of gate resistor

t = f(R_g)



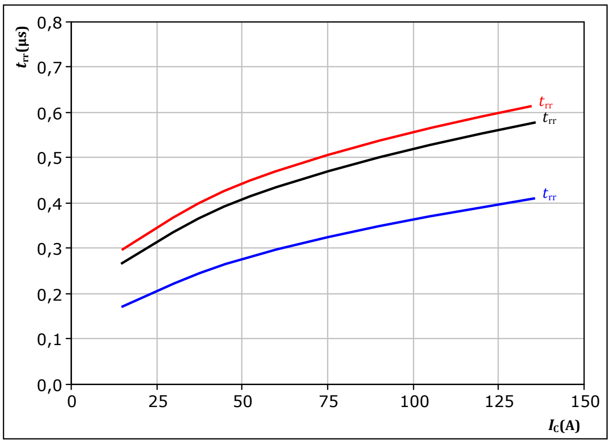
With an inductive load at

T_j =	150	°C
V_{CE} =	700	V
V_{GE} =	0/15	V
I_C =	75	A

figure 42. **FWD**

Typical reverse recovery time as a function of collector current

t_{rr} = f(I_C)



With an inductive load at

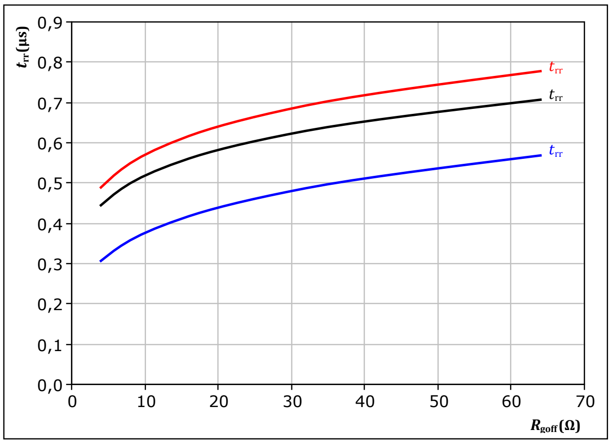
V_{CE} =	700	V
V_{GE} =	0/15	V
R_{gon} =	4	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 43. **FWD**

Typical reverse recovery time as a function of IGBT turn off gate resistor

t_{rr} = f(R_{goff})



With an inductive load at

V_{CE} =	700	V
V_{GE} =	0/15	V
I_C =	75	A

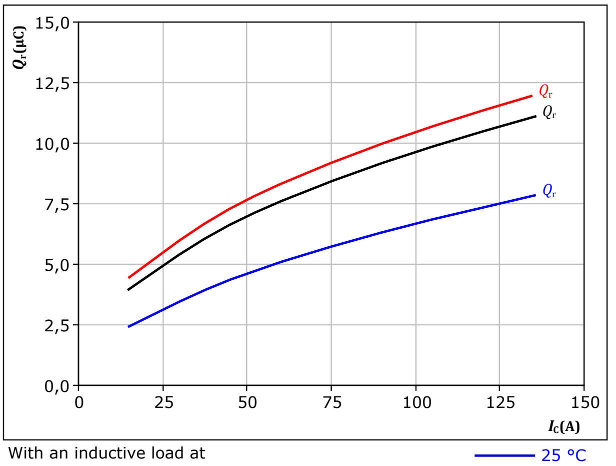
T_j: 25 °C, 125 °C, 150 °C

Brake Switching Characteristics

figure 44. **FWD**

Typical recovered charge as a function of collector current

Q_r = f(I_C)



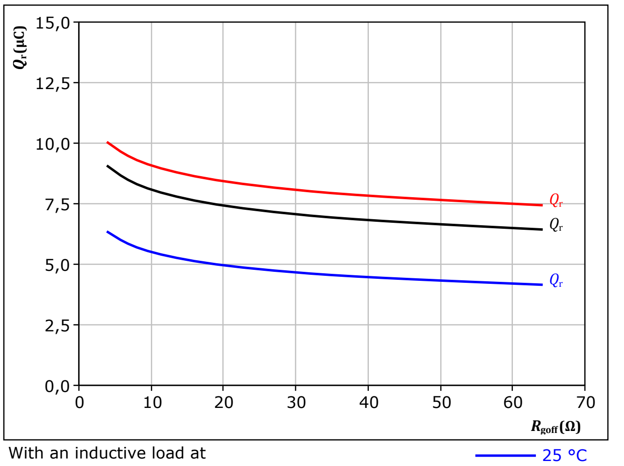
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	4	Ω		150 °C

figure 45. **FWD**

Typical recovered charge as a function of turn off gate resistor

Q_r = f(R_{goff})



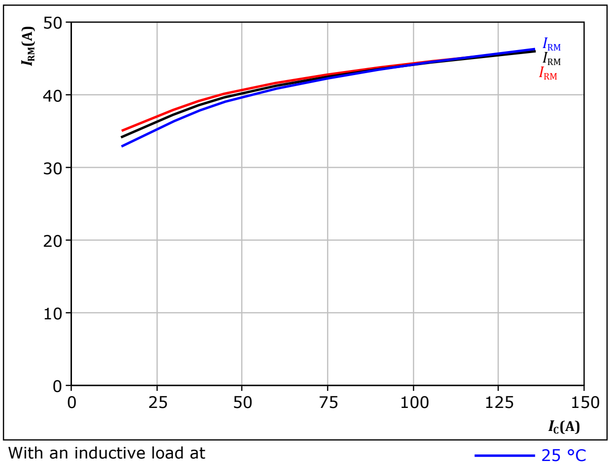
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	75	A		150 °C

figure 46. **FWD**

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



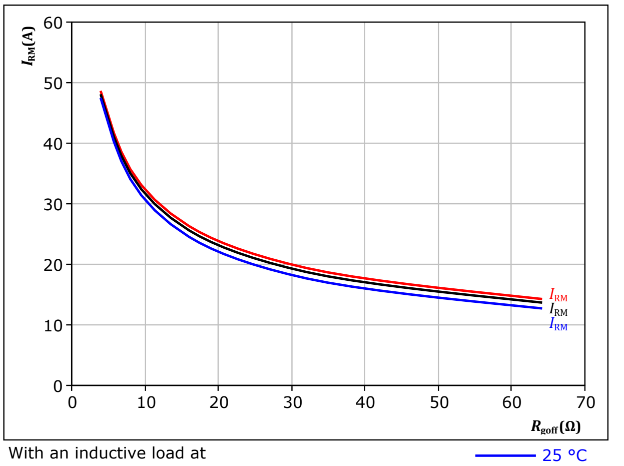
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	4	Ω		150 °C

figure 47. **FWD**

Typical peak reverse recovery current as a function of turn off gate resistor

I_{RM} = f(R_{goff})



With an inductive load at

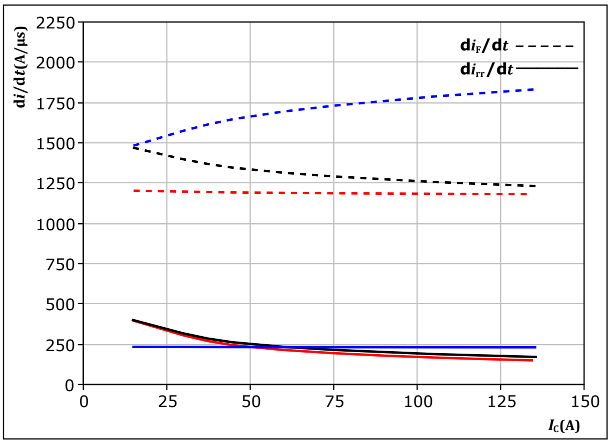
V_{CE} =	700	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	75	A		150 °C

Brake Switching Characteristics

figure 48. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



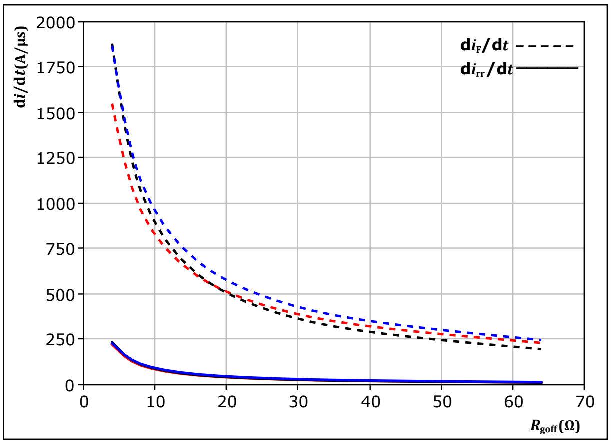
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	4	Ω		150 °C

figure 49. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn off gate resistor

di_F/dt, di_{rr}/dt = f(R_{goff})



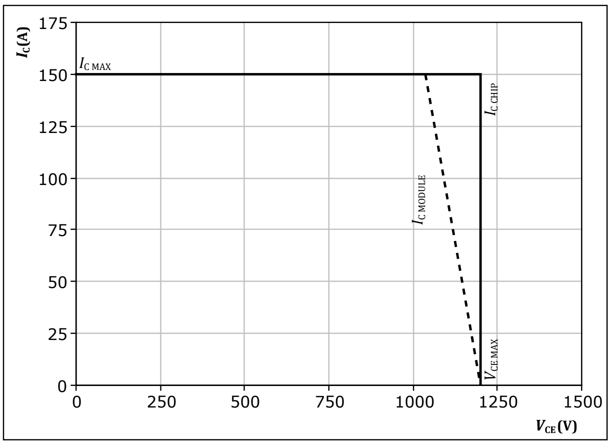
With an inductive load at

V_{CE} =	700	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	75	A		150 °C

figure 50. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



At	T_j =	150	°C
	R_{gon} =	4	Ω
	R_{goff} =	4	Ω

Switching Definitions

figure 51. **IGBT**

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} = integrating time for E_{off})

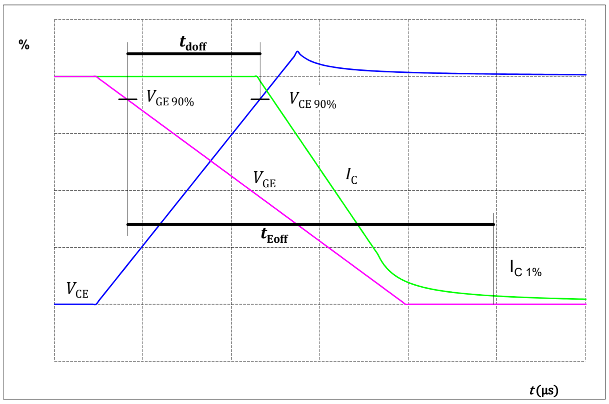


figure 52. **IGBT**

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})

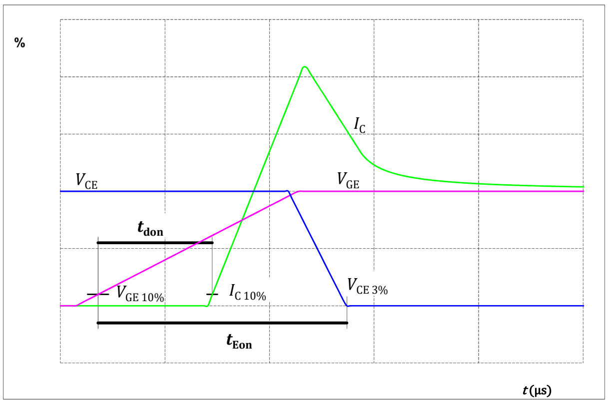


figure 53. **IGBT**

Turn-off Switching Waveforms & definition of t_f

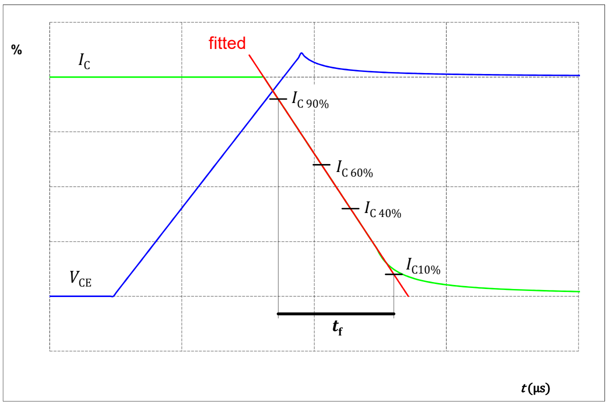
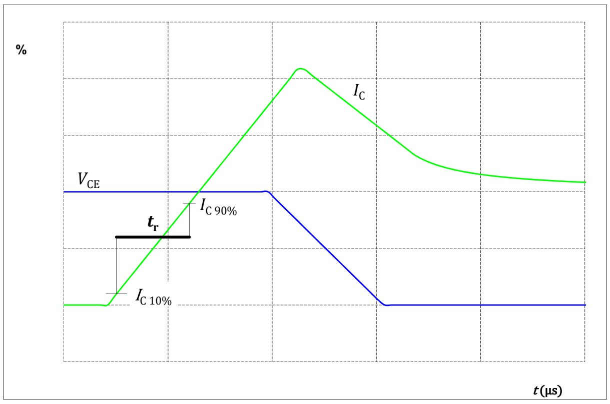


figure 54. **IGBT**

Turn-on Switching Waveforms & definition of t_r



Switching Definitions

figure 55.	FWD

Turn-off Switching Waveforms & definition of t_{rr}

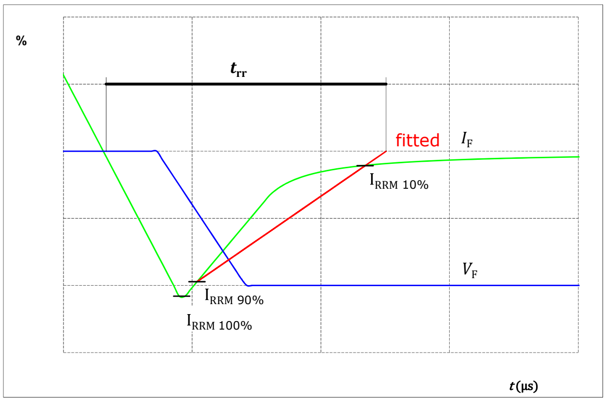
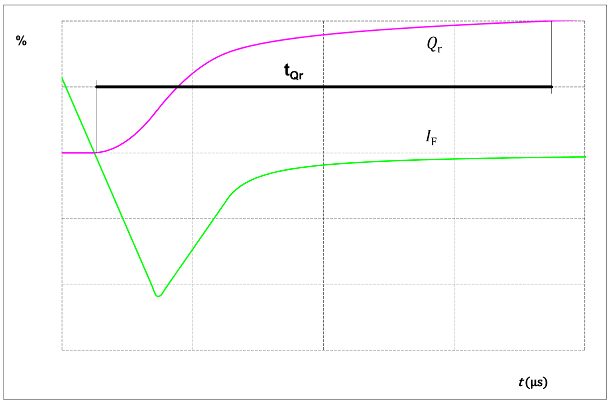


figure 56.	FWD

Turn-on Switching Waveforms & definition of t_{Qr} **(**t_{Qr} **= integrating time for** Q_r**)**



Ordering Code

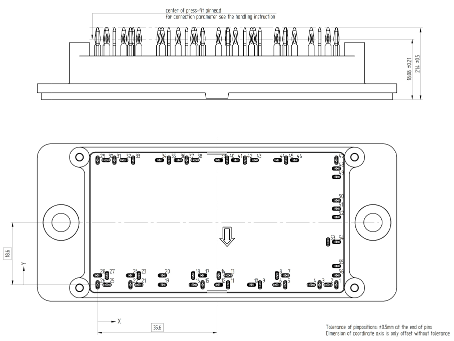
Version	Ordering Code
Without thermal paste	30-P212PMA100M7-L880A79Y
With thermal paste (3,4 W/mK, PSX-P7)	30-P212PMA100M7-L880A79Y-/3/

Marking

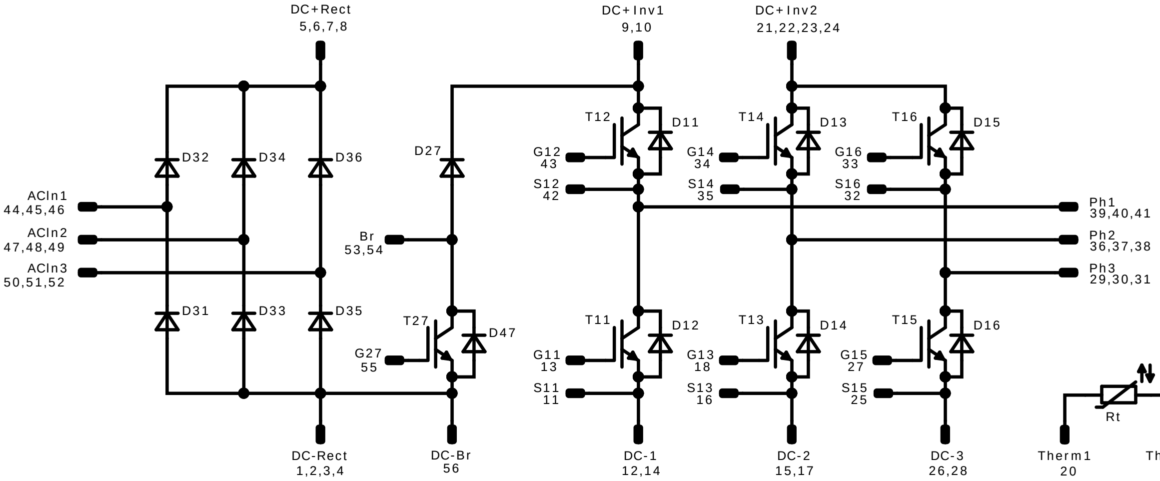
	**Text**	**Name**		**Date code**	**UL & VIN**	**Lot**	**Serial**
		NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
	Datamatrix	**Type&Ver**	**Lot number**	**Serial**	**Date code**		
		TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

Pin table [mm]							
Pin	X	Y	Function	29	0	37,2	Ph3
1	71,2	0	DC-Rect	30	2,5	37,2	Ph3
2	68,7	0	DC-Rect	31	5	37,2	Ph3
3	66,2	0	DC-Rect	32	7,8	37,2	S16
4	63,7	0	DC-Rect	33	10,6	37,2	G16
5	55,95	0	DC+Rect	34	18,45	37,2	G14
6	53,45	0	DC+Rect	35	21,25	37,2	S14
7	55,95	2,8	DC+Rect	36	24,05	37,2	Ph2
8	53,45	2,8	DC+Rect	37	26,55	37,2	Ph2
9	48,4	0	DC+Inv1	38	29,05	37,2	Ph2
10	45,9	0	DC+Inv1	39	36,1	37,2	Ph1
11	38,9	0	S11	40	38,6	37,2	Ph1
12	36,1	0	DC-1	41	41,1	37,2	Ph1
13	38,9	2,8	G11	42	43,9	37,2	S12
14	36,1	2,8	DC-1	43	46,7	37,2	G12
15	31,3	0	DC-2	44	53,7	37,2	ACIn1
16	28,5	0	S13	45	56,2	37,2	ACIn1
17	31,3	2,8	DC-2	46	58,7	37,2	ACIn1
18	28,5	2,8	G13	47	71,2	37,2	ACIn2
19	19,3	0	Therm2	48	71,2	34,7	ACIn2
20	19,3	2,8	Therm1	49	71,2	32,2	ACIn2
21	12,3	0	DC+Inv2	50	71,2	25,2	ACIn3
22	9,8	0	DC+Inv2	51	71,2	22,7	ACIn3
23	12,3	2,8	DC+Inv2	52	71,2	20,2	ACIn3
24	9,8	2,8	DC+Inv2	53	68,7	12,8	Br
25	2,8	0	S15	54	71,2	12,8	Br
26	0	0	DC-3	55	71,2	5,6	G27
27	2,8	2,8	G15	56	71,2	2,8	DC-Br
28	0	2,8	DC-3				



Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	100 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	100 A	Inverter Diode	
T27	IGBT	1200 V	75 A	Brake Switch	
D27	FWD	1200 V	35 A	Brake Diode	
D47	FWD	1200 V	5 A	Brake Sw. Protection Diode	
D31, D32, D33, D34, D35, D36	Rectifier	1600 V	75 A	Rectifier Diode	
Rt	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 36	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 2 packages see vincotech.com website.

Package data
Package data for *flow* 2 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
30-P212PMA100M7-L880A79Y-D5-14	25 Sep. 2021	Updated maximum current Updated clearance Rectifier forward voltage condition changed Brake diode forward voltage is updated Brake Sw. Protection Diode thermal characteristics updated Separated datasheet for press-fit pin version New datasheet format module is unchanged	